What is claimed is:

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1. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein the plurality of heat-dissipating fins on each heat-dissipating portion are grouped into at least two groups of fins and the groups are separated from each other for mounting of the heatsink on an electronic component with a clip fitting on the electronic component between the groups of the fins.

2. The heatsink of claim 1, wherein each heat-dissipating portion of an individual heatsink plate has one protrusion which contacts an adjacent heat-dissipating plate so that each heat-dissipating plate is displaced at an angle from adjacent heat-dissipating plates in the heatsink.

3. The heatsink of claim 1, wherein the binding portions of individual heatsink plates have at least one pair of a protrusion and an indentation which are complementary and engaged with a protrusion and an indentation, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.

4. The heatsink of claim 2, wherein the binding portions of the individual heatsink plates have at least one pair of a protrusion and an indentation which are complementary and engaged with a protrusion and an indentation, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.

5. The heatsink of claim 1, comprising a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring

heatsink plates, wherein the spacers have extensions extending from the plurality of binding portions.

6. The heatsink of claim 5, wherein each heat-dissipating portion of an individual heatsink plate has one protrusion which contacts an adjacent heat-dissipating plate so that each heat-dissipating plate is displaced at an angle from adjacent heat-dissipating plates in the heatsink.

7. The heatsink of claim 5, wherein the binding portions of the individual heatsink plates and the spacers have at least one pair of a protrusion and an indentation which are complementary with a protrusion and an indentation, respectively, of another heatsink plate, for preventing distortion of the binding portions.

8. The heatsink of claim 6, wherein the binding portions of the individual heatsink plates and the spacers have at least one pair of a protrusion and an indentation which are complementary with a protrusion and an indentation, respectively, of another heatsink plate, for preventing distortion of the binding portions.

9. The heatsink of claim 1, comprising a fan installed at the heatsink to blow air over the heatsink.

10. The heatsink of claim 2, comprising a fan installed at the heatsink to blow air over the heatsink.

11. The heatsink of claim 3, comprising a fan installed at the heatsink to blow air over the heatsink.

12. The heatsink of claim 1, comprising a bracket and a fan fitted to the bracket, to blow air over the heatsink.

13. The heatsink of claim 2, comprising a bracket and a fan fitted to the bracket, to blow air over the heatsink.

14. The heatsink of claim 3, comprising a bracket and a fan fitted to the bracket, to blow air over the heatsink.

15. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein each heat-dissipating fin in the heat-dissipating portion has a protrusion contacting an adjacent heat-dissipating fin and displacing the heat-dissipating plate from the adjacent heat-dissipating plate.

16. The heatsink of claim 15 wherein the plurality of heat-dissipating fins on each heat-dissipating portion are grouped into at least two groups of fins and the groups are separated from each other for mounting of the heatsink on an electronic component with a clip fitting on the electronic component between the groups of the fins.

17. The heatsink of claim 15, wherein the binding portions of individual heatsink plates have at least one pair of a protrusion and an indentation which are complementary and engaged with a protrusion and an indentation, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.

18. The heatsink of claim 15, comprising a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring heatsink plates, wherein the spacers have extensions extending from the plurality of binding portions.

19. The heatsink of claim 18, wherein each heat-dissipating portion of an individual heatsink plate has one protrusion which contacts an adjacent heat-dissipating plate so that each heat-dissipating plate is displaced at an angle from adjacent heat-dissipating plates in the heatsink.

20. The heatsink of claim 18, wherein the binding portions of the individual heatsink plates and the spacers have at least one pair of a protrusion and an indentation which are complementary with a protrusion and an indentation, respectively, of another heatsink plate, for preventing distortion of the binding portions.

21. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein each heat-dissipating portion of an individual heatsink plate has one protrusion which contacts an adjacent heat-dissipating plate so that each heat-dissipating plate is displaced at an angle from adjacent heat-dissipating plates in the heatsink.

22. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions; and

means for binding the plurality of heatsink plates together, wherein the binding portions of individual heatsink plates have at least one pair of a protrusion and an indentation which are complementary and engaged with a protrusion and an indentation, respectively, of another heatsink plate for maintaining registration of and preventing distortion of the binding portions.

23. A heatsink for an electronic component comprising:

a plurality of heatsink plates, each of the heatsink plates having a binding portion and a heat-dissipating portion, each heat-dissipating portion including a plurality of heat-dissipating fins joined to the binding portion, wherein the heatsink plates are bound together at the binding portions to form a heat-absorbing portion for contacting a heat-dissipating surface of an electronic component, and at least some of the heat-dissipating portions of the heatsink plates are bent at angles relative to the respective binding portions of the heatsink plates to increase separation between adjacent heat-dissipating portions;

means for binding the plurality of heatsink plates together; and

a plurality of spacers, each spacer being interposed between the binding portions of a respective pair of neighboring heatsink plates, wherein the spacers have extensions extending from the plurality of binding portions.